

N-Ch MOSFET

General Description

The WST3424 is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST3424 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

Product Summery

BVDSS	RDSON	ID
20V	50mΩ	4.4A

Applications

- High Frequency Point-of-Load Synchronous s Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

SOT-23-3L Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units	
V _{DS}	Drain-Source Voltage	20	V	
V _{GS}	Gate-Source Voltage	±12	V	
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	4.4	А	
I _D @T _C =70℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	3.2	А	
I _{DM}	Pulsed Drain Current ²	12	А	
P _D @T _A =25℃	Total Power Dissipation ³	1.0	W	
T _{STG}	Storage Temperature Range -55 to 150		°C	
TJ	Operating Junction Temperature Range	-55 to 150	°C	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit	
R _{0JA}	Thermal Resistance Junction-ambient ¹		200	°C/W	
R _{θJC}	Thermal Resistance Junction-Case ¹		75	°C/W	



N-Ch MOSFET

Electrical Characteristics (T_J=25¹C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	20			V
$\bigtriangleup BV_{\text{DSS}} / \bigtriangleup T_{\text{J}}$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$, I_D=1mA		0.024		V/℃
	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =1.8A		50	65	mΩ
R _{DS(ON)}		V _{GS} =2.5V , I _D =1.5A		60	75	
		V _{GS} =1.8V , I _D =1A		70	90	
$V_{GS(th)}$	Gate Threshold Voltage		0.3	0.85	1.2	2 V mV/°C
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS} = V_{DS}$, $I_D = 2500A$		-2.51		
1	Drain Source Leekage Current	V _{DS} =16V , V _{GS} =0V , T _J =25℃			1	
I _{DSS}	Drain-Source Leakage Current	V_{DS} =16V , V_{GS} =0V , T_{J} =55 $^{\circ}$ C			5	- uA
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 8V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =3A		8.3		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		1.7	3.4	Ω
Qg	Total Gate Charge (4.5V)			6.4		
Q_gs	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =1A		0.54		nC
Q_gd	Gate-Drain Charge			1.25		1
T _{d(on)}	Turn-On Delay Time	V _{DD} =10V , V _{GS} =4.5V , R _G =3.3Ω I _D =1A		1.6		
Tr	Rise Time			29.6		
T _{d(off)}	Turn-Off Delay Time			18.8		ns
T _f	Fall Time			6		
Ciss	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		382		
C _{oss}	Output Capacitance			41		pF
C _{rss}	Reverse Transfer Capacitance			33		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,4}				4.3	А
I _{SM}	Pulsed Source Current ^{2,4}	V _G =V _D =0V , Force Current			12	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25℃			1.2	V
t _{rr}	Reverse Recovery Time			5.5		nS
Qrr	Reverse Recovery Charge	l ⊧=2A , dl/dt=100A/µs , Tյ=25 ℃		1.8		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper ,t<10sec.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

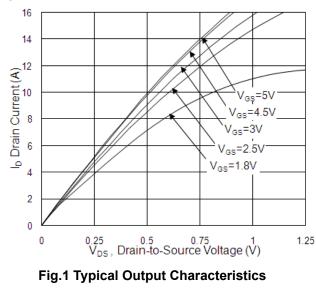
3.The power dissipation is limited by 150 $^\circ \! \mathrm{C}$ junction temperature

4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



N-Ch MOSFET

Typical Characteristics



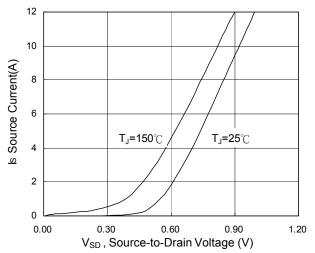


Fig.3 Forward Characteristics Of Reverse

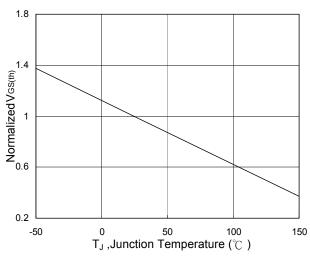


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

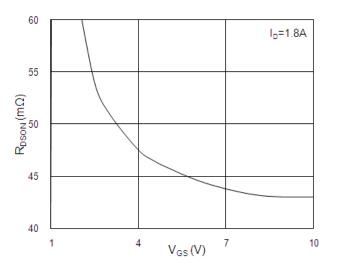


Fig.2 On-Resistance vs. Gate-Source

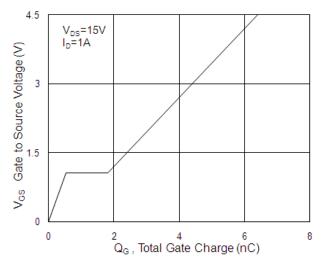


Fig.4 Gate-Charge Characteristics

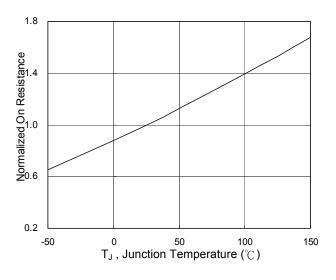


Fig.6 Normalized R_{DSON} vs. T_J



N-Ch MOSFET

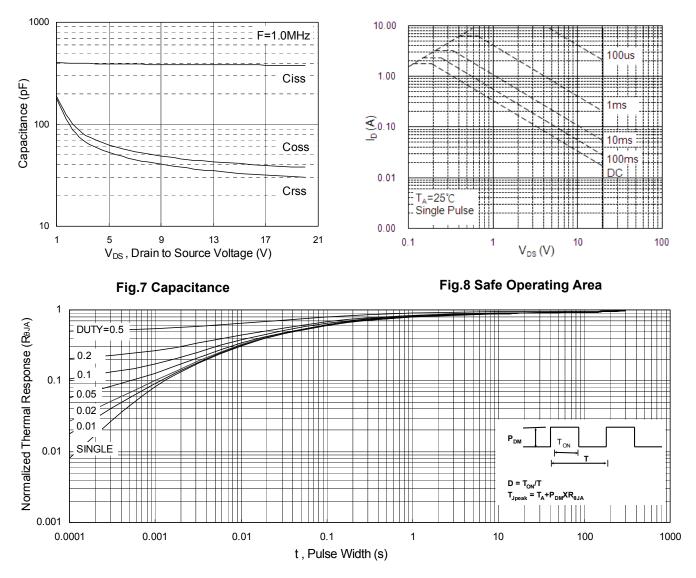
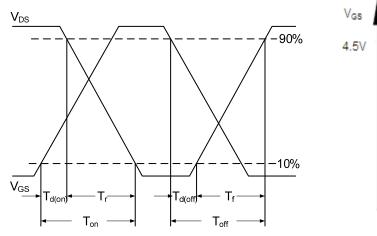
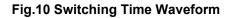


Fig.9 Normalized Maximum Transient Thermal Impedance





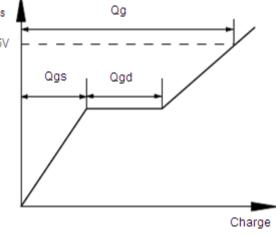


Fig.11 Gate Charge Waveform



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